

Quik-Pak Wins IMAPS 2016 Corporate Recognition Award for Significant Technical Contributions to the Microelectronics Industry

IC Packaging Solutions Provider Receives Award at IMAPS 49th International Symposium on Microelectronics, Oct. 11-12, Pasadena, CA; Exhibits in Booth 622

San Diego, CA – October 11, 2016 – [Quik-Pak](#), a provider of microelectronic chip packaging and assembly solutions, will receive the International Microelectronics Assembly and Packaging Society (IMAPS) 2016 Corporate Recognition Award at the industry organization's [49th International Symposium on Microelectronics](#) on October 11, 2016 in Pasadena, Calif. IMAPS grants the annual award to one corporation that has made significant technical contributions to the microelectronics industry, supported educational activities and participated in IMAPS-sponsored events.

“Our unique, repurposed [Open Cavity Plastic Packages](#) (OcPP), along with our on-shore prototype wafer preparation and assembly services, have enabled numerous customers – including startups and fabless companies – to rapidly bring their ideas to fruition and successfully launch them into the marketplace,” said Quik-Pak Director of Sales and Marketing Casey Krawiec. “In addition, we support universities, national laboratories, and research facilities around the world, encompassing a wide range of industries beyond microelectronics.”

Quik-Pak will exhibit [newly manufactured air cavity QFNs](#), repurposed packages, over-molded plastic QFN/DFN packages and other capabilities in Booth 622 at IMAPS 2016, October 11-12. An IMAPS premier corporate member, Quik-Pak recently exhibited at IMAPS' Advanced Technology Workshop in New York and sponsored IMAPS San Diego Chapter's technical presentation.

“Quik-Pak has been at the forefront of microelectronics prototype and packaging services for 20 years and is now part of the fabric and infrastructure of the electronics industry,” said Promex CEO Richard Otte. “The company continues to set the standard for rapid device packaging, including providing a full suite of IC packaging options available in three days or less.”

About Open Cavity Plastic Packages

The OcPP process is a unique method for removing the original die (if present) from a molded plastic IC package, then wire bonding and encapsulating a new die into the exact same package. The assembled units can be left "open" with the die exposed for electrical probing or visual inspection, or encapsulated and re-marked.

About Quik-Pak

Quik-Pak's Open Cavity capability and complementary turn-key assembly services continue to provide a strategic time-to-market advantage for semiconductor innovators. From its San Diego, Calif. facility and East Coast office in Vermont, the company offers services from prototype design validation to full production, as well as wafer preparation services, including backgrinding, dicing, and pick and place.

Quik-Pak is a division of [Promex](http://www.promex-ind.com), a Silicon Valley-based company offering package engineering services and mixed assembly (combinations of SMT, die attach, wire bonding, encapsulation, etc.) for medical, biotech, military and commercial applications. More information about **Quik-Pak** is available at www.icproto.com or by calling 858-674-4676. More information about **Promex** is available at www.promex-ind.com or by calling 408-496-0222.

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Caption:

Quik-Pak will receive the IMAPS 2016 Corporate Recognition Award at the International Symposium on Microelectronics, October 11-12. In Booth 622, Quik-Pak will exhibit newly manufactured air cavity QFNs, repurposed packages, over-molded plastic QFN/DFN packages and other capabilities. Quik-Pak's repurposed Open Cavity Plastic Packages (OcPP), along with on-shore prototype wafer preparation and assembly services, have enabled customers – including startups and fabless companies – to rapidly bring ideas to fruition and successfully launch them into the marketplace. Photo source: www.imaps.org